

NOTES:

1) MATERIAL:

HOUSING: HI-TEMP. PLASIC UL 94V-0

CONTACT: COPPER ALLOY

SHELL: STAINLESS STEEL

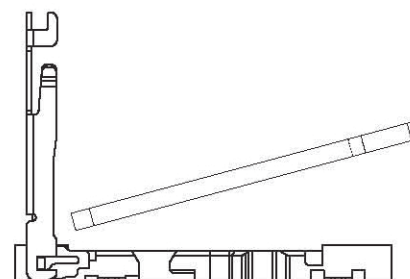
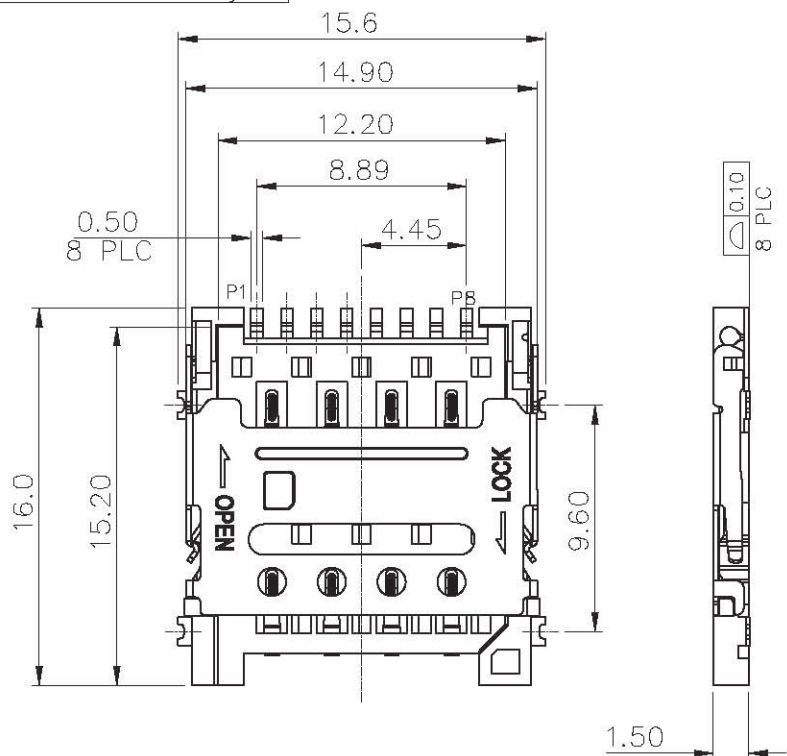
2) FINISH:

CONTACT: GOLD FLASH PLATED ON CONTACT AREA

GOLD FLASH PLATED ON SOLDER TAILS,

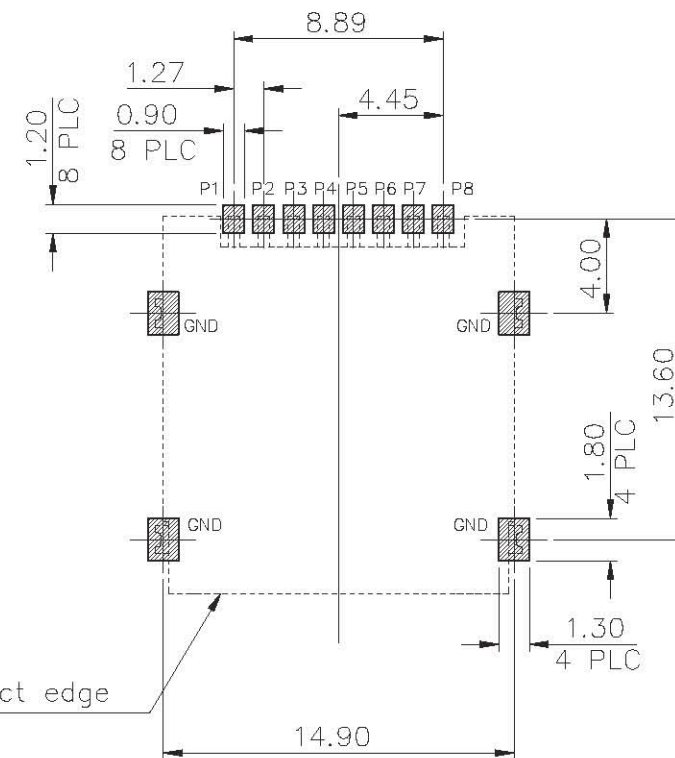
3) PART NO.:

ASMF S 150 N XX B R 081
SMT TYPE
APPEARANCE
SHELL PLATED
N: NONE PLATED
CONTACT PLATED
01: 1u"
03: 3u"
05: 5u"
10: 10u"
PACK: T/R
B: BLACK

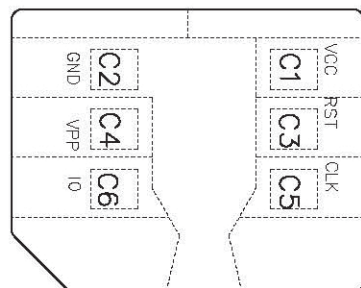


OPEN (INSERT SIM CARD)

LOCK (PUSH SHELL)



RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES: ± 0.05



芯片面朝下视图

MICRO SIM CARD	
PIN NO.	DESCRIPTION
P1	VCC
P2	GND
P3	RST
P4	VPP
P5	CLK
P6	I/O
P7	RESERVED
P8	RESERVED

GENERAL TOLERANCE		图号	A1505-001	设计	许小伟	比例	1:1
$X \pm 0.35$	$x' \pm 5^\circ$	品名	MICRO SIM CARD 8PIN 1.5H (掀盖式8X1PIN)	审核		单位	mm
$.X \pm 0.30$	$.x' \pm 2^\circ$			核准		视角	
$.XX \pm 0.20$	$.xx' \pm 1^\circ$	料号	ASMFS150N01BR081	日期	2015/05/06	版本	A
$.XXX \pm 0.15$	$.xxx' \pm 0.5^\circ$	页号	1/1	东莞市涪程电子科技有限公司			